

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s) : Franz LAERMER et al.  
Serial No. : 10/530,612  
Filed : December 30, 2005  
For : **PLASMA SYSTEM AND METHOD FOR  
ANISOTROPICALLY ETCHING STRUCTURES  
INTO A SUBSTRATE**  
  
Art Unit : 1792  
Examiner : Maki A. Angadi  
Confirmation No. : 6739

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I hereby certify that this correspondence is being electronically transmitted to the United States Patent and Trademark Office via the Office electronic filing system on <u>May 4, 2009</u> . Signature: /Gerard A. Messina/
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**REPLY UNDER 37 C.F.R. § 1.116**

SIR:

In response to a December 3, 2008 Final Office Action in the above-identified application, please amend, without prejudice, the above-captioned application as follows.

**Amendments to the Claims** are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

**Remarks** begin on page 7 of this paper.